

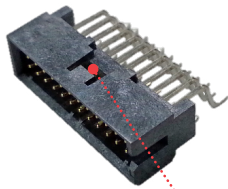
Slim-Grid 1.27mm Pitch Board-to-Board Connector

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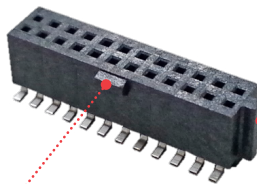
Based on a 1.27 by 1.27mm grid pattern, this high-current density board-to-board interconnect solution offers complete design flexibility and higher current density per inch to support variety of data, automotive, industrial and consumer board-to-board applications

Features and Benefits

Shrouded Right Angle Header, Horizontal SMT



Vertical Receptacle, SMT



Locking Window, Locking Ramp

Ensure robust connector retention when mated

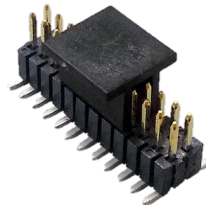
Single-sided Polarization Slot

Prevents wrong orientation and mis-mating.
Improves mating for smaller circuit sizes of 6 and below

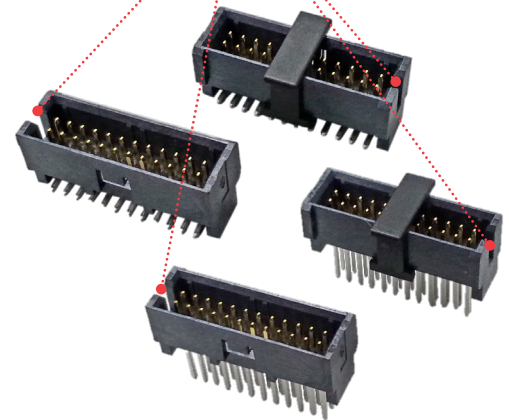


Locating Pegs (Shrouded Right Angle Header, Through-hole)

Ensure precise connector positioning on PCB



Vertical Unshrouded Headers with Pick-and-Place Cap, SMT



Vertical Shrouded Headers with and without Pick-and-Place Cap, SMT and Through-hole



Slim-Grid 1.27mm Pitch Board-to-Board Connectors

Applications

Consumer / Smart House

- Energy efficient appliances
- Home theaters
- White goods
- Drones

Telecommunications/Networking

- Hubs, Servers, Routers, Switches

Automotive

- Car audio and navigation systems

General Market

- Control boards, Lighting luminaries,
- Audio speakers

Mobile

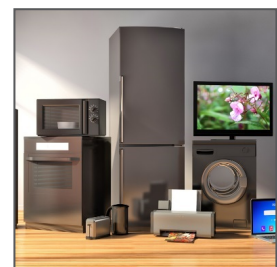
- Smart phones and other portable electronic devices



Drones



Car Audio and Navigation System



Home Appliances

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Specifications

REFERENCE INFORMATION

Packaging: Tube, Tape and Reel upon request
UL File No.: E29179, Vol. 10
CSA File No.: 152514 (LR 19980)
Mates With: 87933/200989/201021/201022 and 201173
Terminal Used: Copper Alloy
Designed In: Millimeters
RoHS: Yes
Halogen Free: Yes
Glow Wire-compliant: Pending for application

ELECTRICAL

Voltage (max.): 125V AC
Current (max.): 4.3A (per circuit)
Contact Resistance: 30 milliohms
Insulation Resistance: 1000 Megohms

MECHANICAL

Terminal Retention Force (in Housing): 2.22N
Terminal Retention Force (Header): 4.0N
Mating Force: 10N (4-circuit) to 15N (24-circuit)
Unmating Force: 0.5N (4-circuit) to 3.0N (24-circuit)
Durability (min.): 50 cycles

PHYSICAL

Housing: LCP, UL94V-0 Black
Contact: Copper Alloy
Plating:
Contact Area — 0.05, 0.38 and 0.76micron Gold (Au)
Solder Tail Area — 2.00 micron Matte Tin (Sn)
Underplating — 1.27 micron Nickel (Ni)
PCB Thickness: Refer to sales drawing
Operating Temperature: -55 to 105°C

Ordering Information

Series No.	Description	Part No. / LEGEND
78120	Vertical SMT Receptacle	78120-AA AA - circuit size (04 to 24) B - packaging option C - plating option
200989	Vertical SMT Shrouded Header	200989-ABCC A - packaging option B - plating option CC - circuit size (04 to 24)
201022	Shrouded Vertical Through-hole Header	201022-ABCC A - packaging option B - plating option CC - circuit size (04 to 24)
201173	Shrouded Right Angle SMT Header	201173-ABCC A - packaging option B - plating option CC - circuit size (04 to 24)
201021	Shrouded Right Angle Through-hole Header	201021-ABCC A - packaging option B - plating option CC - circuit size (04 to 24)
87933	Unshrouded Vertical SMT Header	87933-AA AA - circuit size (04 to 24) BB - plating/package option

www.molex.com/link/slimgrid.html